

Amendments to the Specification:

Please replace the **Abstract** with the following amended Abstract:

An apparatus for transferring heat from semiconductor devices during a burn-in ~~procedure~~ operation is disclosed. The apparatus ~~comprises~~ includes a substantially planar base board member that includes through which a plurality of openings ~~extending through the base member, are extended~~. at least one heat sink Heat sinks aligned coordinated with ~~each opening, and the openings are connected to~~ biasing members ~~connected to the heat sinks for biasing the heat sinks. and come in contact with the~~ semiconductor devices during the burn-in operation for transferring heat from the devices.

Please replace second paragraph on page 7 with the following amended paragraph:

Referring also to FIG. 2, which is a top-plan view of the heat transfer apparatus [13] 15, the base member 40 includes a plurality of substantially rectangular openings 50 that extend through the base member 40 from the top surface 44 to the bottom surface 46. The openings 50 are arranged in the base member 40 such that each opening 50 corresponds with or overlies one socket 16 of the burn-in board 14 to which the base member 40 is attached. Arranging the openings 50 to correspond with the sockets 16 of the burn-in board allows the sockets 16 as well as semiconductor devices 12 positioned in the sockets 16 to be readily accessed for repair, measurement, and/or visual inspection once the heat transfer apparatus [13] 15 is attached to the burn-in board 14.

Please replace the first paragraph on page 8 with the following amended paragraph:

The heat sink 42 has a bottom portion 60 with a contact surface 62 for contacting an exposed portion of a semiconductor device (not shown) positioned in the socket 16 of the burn-in board 14. The heat sink 42 provides a thermal mass for absorbing heat that is generated by the semiconductor device while the semiconductor device is being tested, and also acts to dissipate heat away from the semiconductor device. The contact surface 62 of the bottom portion 60 of the heat sink 42 can have length and width dimensions (*i.e.*, surface area) equal to or larger than the length and width of the exposed portion of the semiconductor device to provide the largest area of thermal contact between the heat

sink 42 and the semiconductor device. Alternatively, the contact surface 62 can have a surface area that is slightly smaller the surface area of the exposed portion of the semiconductor device. Providing the heat sink 42 with a contact surface [42] 62 that has a surface area slightly smaller than the surface area of the exposed portion of the semiconductor device can be desirable to avoid damaging the edges of the semiconductor device when the heat sink 42 is pressed against the exposed portion of the semiconductor device. It is known that semiconductor devices, such as silicon dice, can be susceptible to cracking at or near the edges of the dice where sheer stress concentration and the possibility of mechanical damage are at their highest.